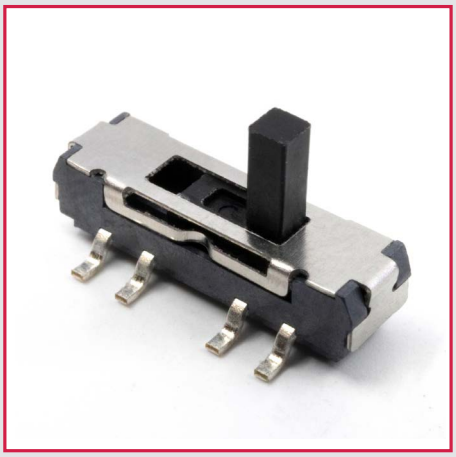
EG2374 Series Slide Switch





Specifications

Contact Rating: 100mA @ 12VDC
Electrical Life: 5,000 Cycles
Contact Resistance: 100mΩ Max.
Insulation Resistance: 100MΩ Min. @ 500VDC
Dielectric Strength: 500VAC for 1 Minute
Operating Temperature: -40°C to 85°C
Storage Temperature: -40°C to 85°C
Travel: 2.00mm from each position to the next position
Contact Arrangement: DP3T - 2-Pole On-On-On
Operating Force: 250 ± 100gf
not recommended for washing processes

Features & Benefits

Surface Mount PC board design
2.00mm travel
Compact design
DP3T function

Part Number Configurator

Series

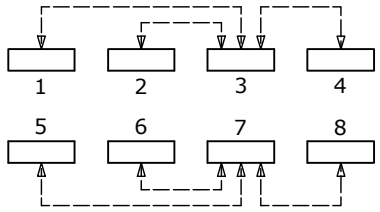
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EG2374

EG2374 Series Slide Switch - Body Dimensions

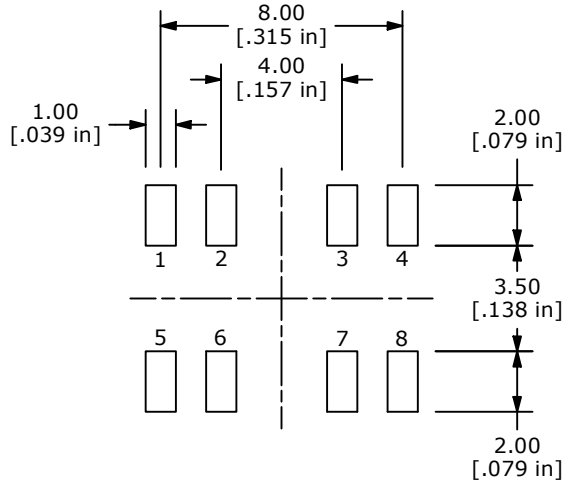
Surface Mount

SWITCH FUNCTION		
POS. 1	POS. 2	POS. 3
ON	ON	ON
1-3, 5-7	2-3, 6-7	3-4, 7-8

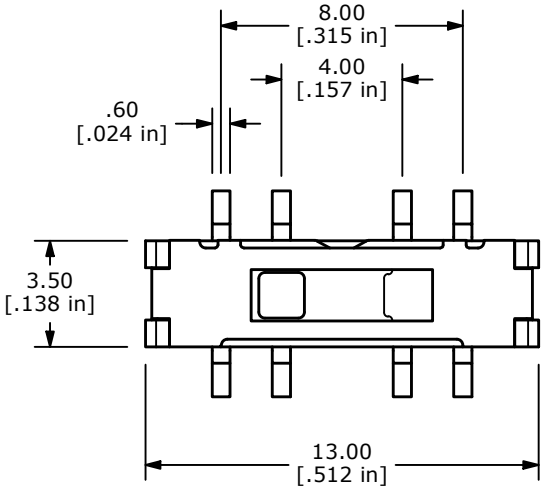


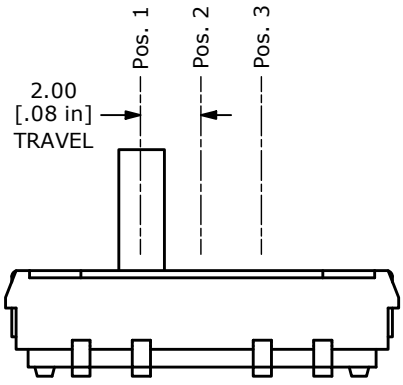
CIRCUIT DIAGRAM

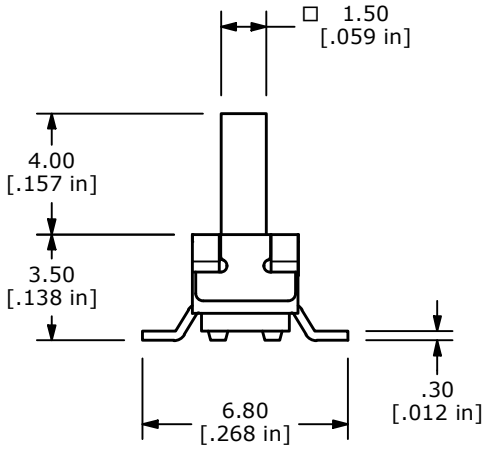
Schematic



Surface Mount PCB Layout

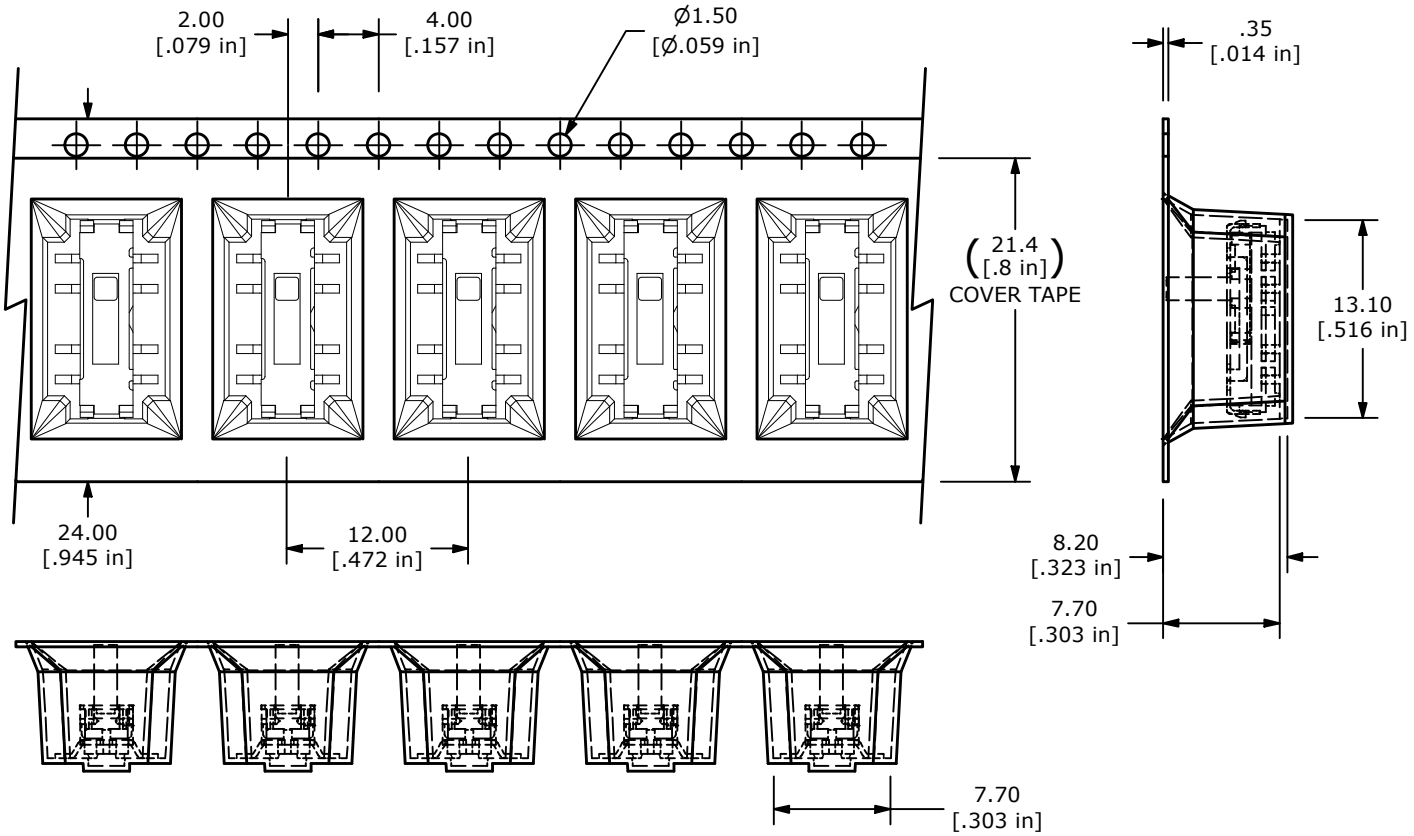


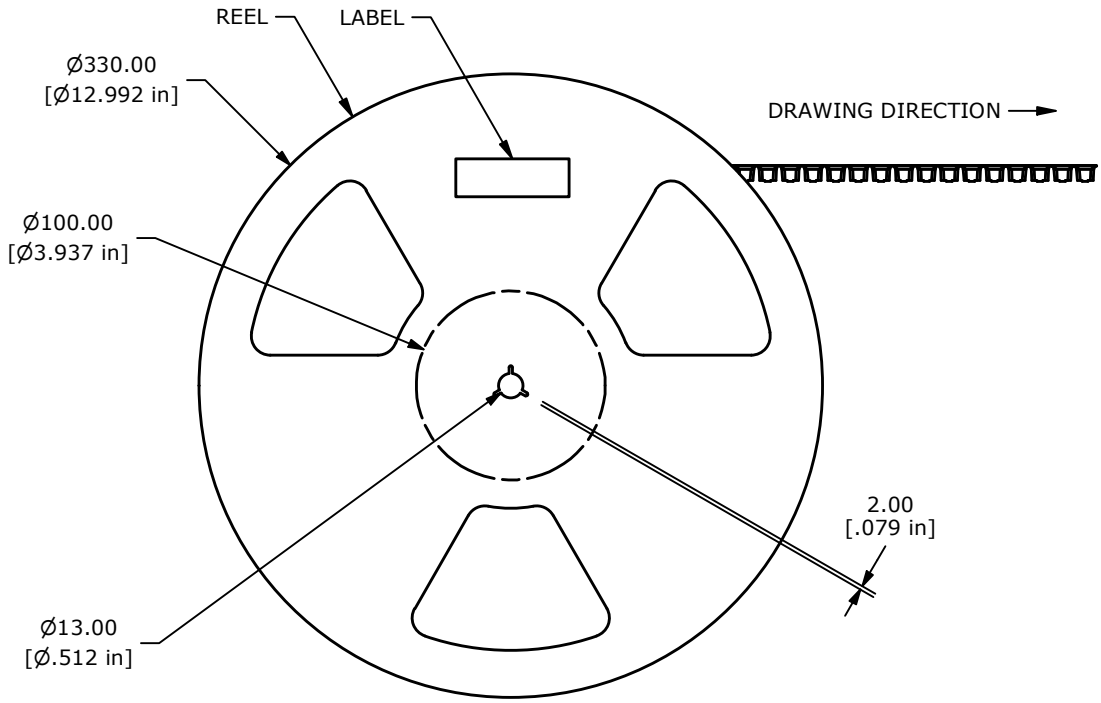




EG2374 Series Slide Switch

Tape and Reel





EG2374 Series Slide Switch

Recommended Solder Process

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

"TYPICAL" SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (Ts_{max} to Tp)	3 °C/second max.	3 °C/second max.
Preheat -Temperature Min (Ts_{min}) -Temperature Max (Ts_{max}) -Time (ts_{min} to ts_{max})	 100 °C 150 °C 60-120 seconds	 150 °C 200 °C 60-180 seconds
Time Maintained above: -Temperature (T_L) -Time (t_L)	 183 °C 60-150 seconds	 217 °C 60-150 seconds
Time within 5 °C of actual Peak Temperature (tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: *All temperatures refer to topside of the package, measured on the package surface.*

